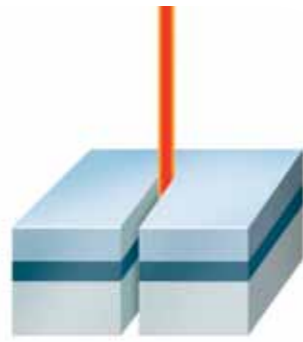
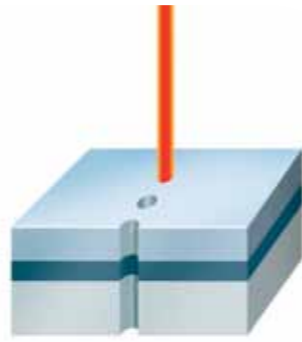


Laser Score



Laser Cut



Laser Micro-Perforation

Web Direction (WD)



Laser Configuration



Score Line



Micro-Perforation

Cross Web (CW)



Laser Configuration



Score Line



Shape Score



Shape Die Cut

ed. 10/2016

FLEXIBLE PACKAGING



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PACKMASTER OEM CW

- Web width: up to 1800 mm
- CW process speed: up to 400 m/min according to the process layout
- Unwinder/re-winder modules: optional
- Process monitoring: optional
- Easy integration on existing production lines



PACKMASTER OEM WD

- Web width: up to 1800 mm
- WD process speed: over 400 m/min according to the process layout
- Unwinder/re-winder modules: optional
- Process monitoring: optional
- Easy integration on existing production lines



Laser FLEXIBILITY for FLEXIBLE packaging

In recent years, packaging has played a strategic role as an element of the product recognition and of product differentiation among the competitors and assisted in the role of communication and marketing strategy.

Food & Beverage and convenience goods producers design effective packaging for the target market taking into account the modern consumer's identity and his needs.

In today's market converters are looking to develop innovative solutions: easy-opening and closing as well as easy-breath, ventilation and window packaging. **SEI Flexible Packaging** is a new line of laser systems which have been designed for laser cutting, laser scoring, macro and micro-perforation of different materials such as PE, PET, PP, nylon, PTFE, laminated film, paper. These systems, in line or standalone, have been developed by SEI Laser R&D Department and the results are now being made available to the professional converter.

Laser cutting, laser scoring, macro and micro laser perforation on flexible film or paper by PACKMASTER OEM CW (Cross Web) and PACKMASTER OEM WD (Web Direction) produce the best results in:

Quality: the main laser features are the precise selective material removal, the laser perforating capability and repeatability of the process. All these features meet the process application needs.

Productivity: up to 400 m/min can be reached in Cross Web (CW) laser cutting, laser scoring and micro-perforation with proprietary beam steering optics galvanometric heads (according to the die-cutting pattern). Over 400 m/min can be reached in Web Direction (WD) laser cutting, laser scoring and micro-perforation with fixed-optics heads.

Flexibility: the all-digital process allows a rapid work change and a significant time and cost reduction (which is not possible in case of traditional mechanical way).



SEI LASER: INNOVATION STILL GOES ON

